



UNITED STATES PATENT AND TRADEMARK OFFICE

25/G
3/27/03
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In re application of:

TONGBI JIANG
EDWARD SCHROCK

MAR 24 2003
TECHNOLOGY CENTER 2800
Adm 15

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

Examiner: PAREKH, N.

Title: BGA PACKAGE HAVING SUBSTRATE
WITH PATTERNED SOLDER MASK
DEFINING OPEN DIE ATTACH AREA
(AS AMENDED)

Attorney Docket No.: 98-0645.1

**AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED
EXAMINATION (RCE) UNDER 37 CFR §1.114**

March 10, 2003

Assistant Commissioner of Patents
BOX RCE
Washington, D.C. 20231

Sir:

This Amendment is in response to the Final Office Action dated December 9, 2002 having a statutory period for response set to expire on March 10, 2003. Please amend the captioned case as follows.

In the Claims:

Please amend independent claims 24, 27, 30 and 34. A clean version of the amended claims, and a clean version of all the pending claims follows. In addition, a marked version of the amended claims showing the changes follows the Remarks section.